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By: 

LINDA E. HASTINGS

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**Attorney Docket No.: NECF 18.363A (100806-00248)**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Inventor : **Hirokazu HONDA**

Conformation No. : **4217**

Serial No. : **10/761,510**

Filed : **January 21, 2004**

Title : **FLIP-CHIP TYPE SEMICONDUCTOR DEVICE AND  
METHOD OF MANUFACTURING THE SAME**

Examiner :

Group Art Unit : **2841**

Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

**PRELIMINARY AMENDMENT**

SIR :

Prior to an Office Action on the merits, please amend the above-captioned  
application as follows: